

Excellent Integrated System Limited

Stocking Distributor

Click to view price, real time Inventory, Delivery & Lifecycle Information:

[STMicroelectronics](#)
[ESDAXLC6-1MY2](#)

For any questions, you can email us directly:

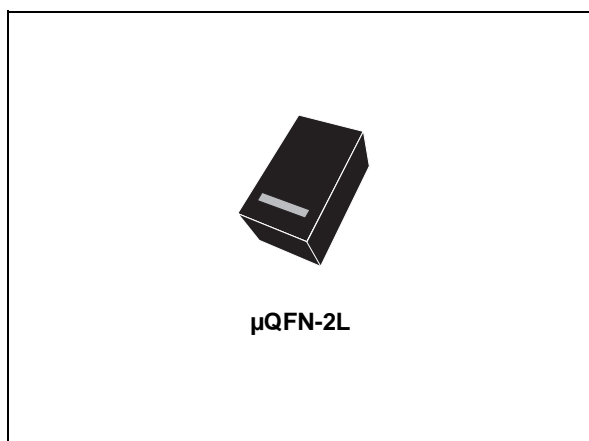
sales@integrated-circuit.com



ESDAXLC6-1MY2

Extra low capacitance single line transient voltage surge suppressor (TVS)

Datasheet - production data



Complies with the following standards

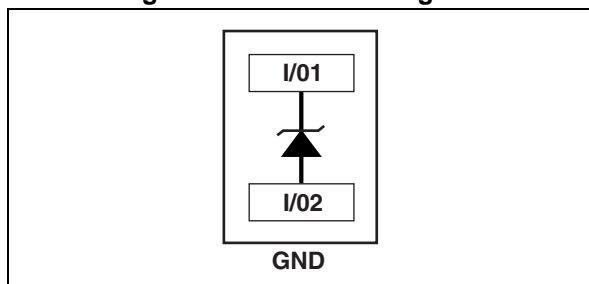
- IEC 61000-4-2 level 4
- MIL STD 883G-Method 3015-7: class 3B

Applications

Where transient over voltage protection and electrical overstress protection in sensitive equipment is required, such as:

- Computers
- Printers
- Communication systems
- Cellular phone handsets and accessories
- Video equipment Portable equipment

Figure 1. Functional diagram



Description

The ESDAXLC6-1MY2 is a single line Transil™ diode designed specifically for the protection of integrated circuits in portable equipment and miniaturized electronics devices subject to ESD transient over voltages. Packaged in μQFN-2L, it minimizes PCB consumption.

Features

- Extra low capacitance 0.6 pF max on a wide frequency spectrum (200 MHz - 3000 MHz)
- Unidirectional device
- Low clamping factor V_{CL}/V_{BR}
- Fast response time
- Very thin package: 0.50 mm max
- Low leakage current
- High ESD protection level
- High integration
- Suitable for high density boards

TM: Transil is a trademark of STMicroelectronics

Characteristics

ESDAXLC6-1MY2

1 Characteristics

Table 1. Absolute maximum ratings ($T_{amb} = 25\text{ }^{\circ}\text{C}$)

Symbol	Parameter	Value	Unit
V_{PP}	Peak pulse voltage: IEC 61000-4-2, level 4: contact discharge	8	kV
P_{PP}	Peak pulse power dissipation (8/20 μs) ⁽¹⁾	$T_{j\text{ initial}} = T_{amb}$ 12	W
I_{PP}	Peak pulse current typical value (8/20 μs)	2.8	A
T_{Op}	Operating junction temperature range	- 40 to + 125	$^{\circ}\text{C}$
T_{stg}	Storage temperature range	- 55 to +150	$^{\circ}\text{C}$

1. For a surge greater than the maximum values, the diode will fail in short-circuit

Figure 2. Electrical characteristics (definitions)

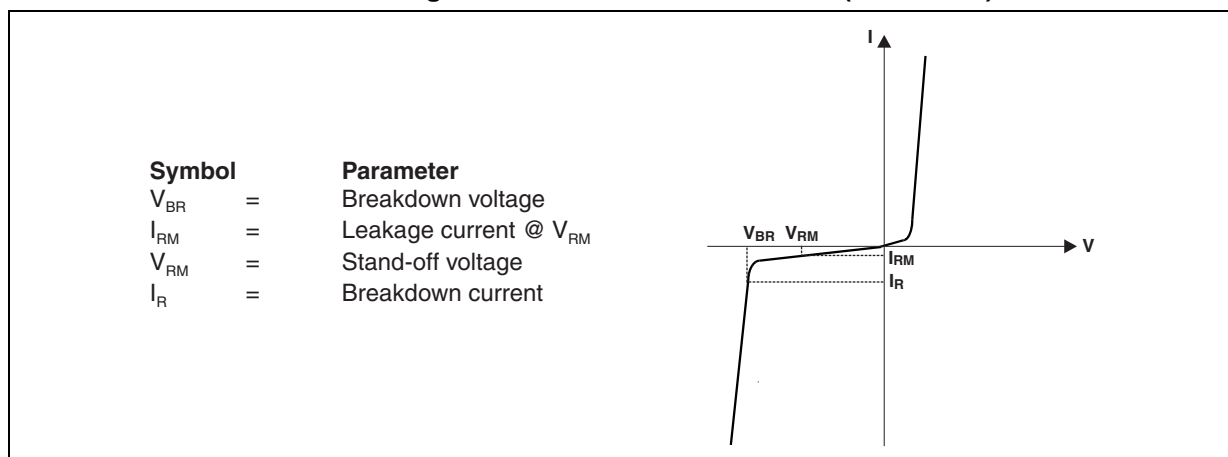


Table 2. Electrical characteristics (values, $T_{amb} = 25\text{ }^{\circ}\text{C}$)

Symbol	Test condition	Min.	Typ.	Max.	Unit
V_{BR}	$I_R = 1\text{ mA}$	6	-	-	V
I_{RM}	$V_{RM} = 3\text{ V}$	-	-	100	nA
C_{line}	$V_R = 0\text{ V}$, $F = (200\text{ MHz} - 3000\text{ MHz})$, $V_{osc} = 30\text{ mV}$	-	-	0.6	pF

ESDAXLC6-1MY2

Characteristics

Figure 3. Junction capacitance versus reverse voltage applied (typical values)

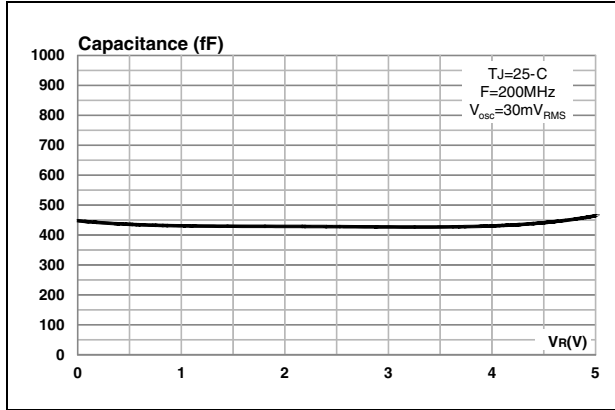


Figure 4. Junction capacitance versus frequency (typical values)

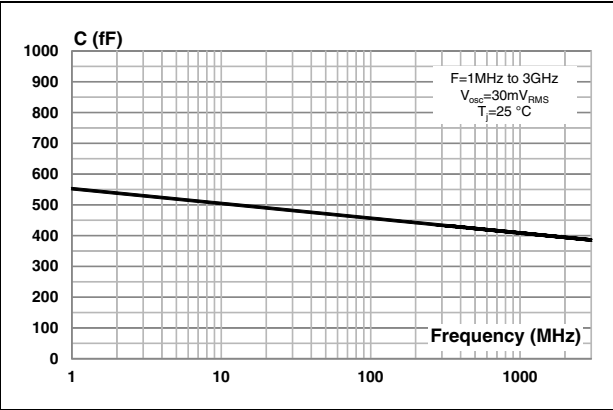


Figure 5. S21 (dB) attenuation

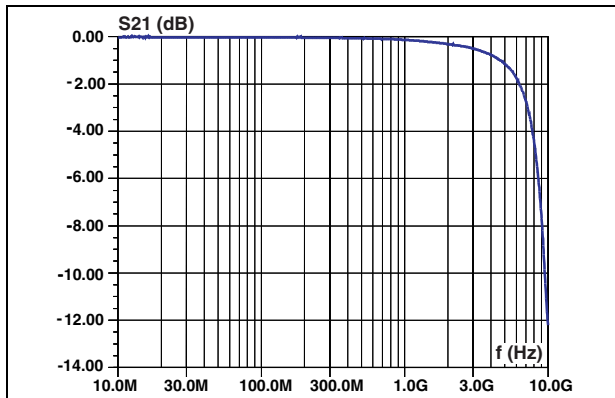


Figure 6. Leakage current versus junction temperature (typical values)

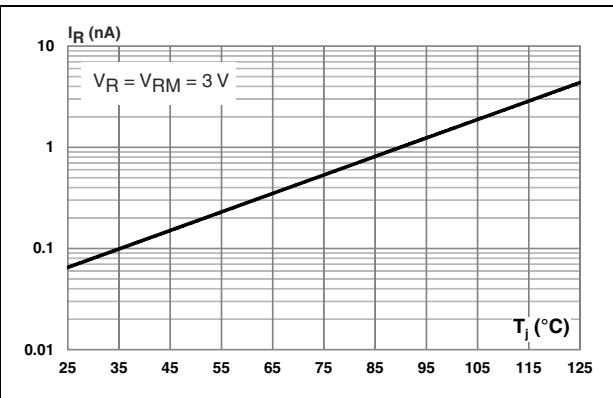


Figure 7. ESD response to IEC 61000-4-2 (+ 8 kV contact discharge)

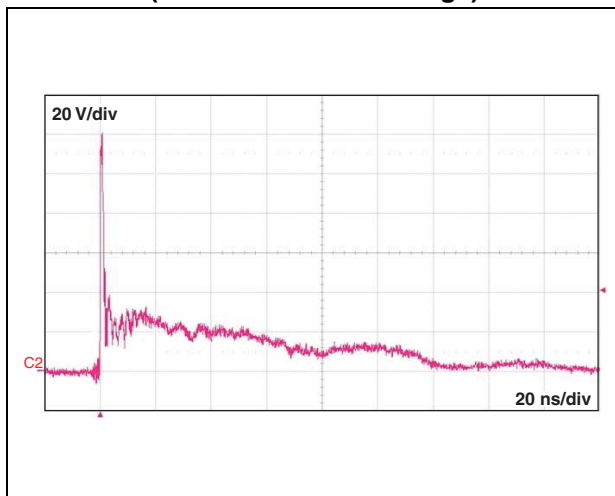
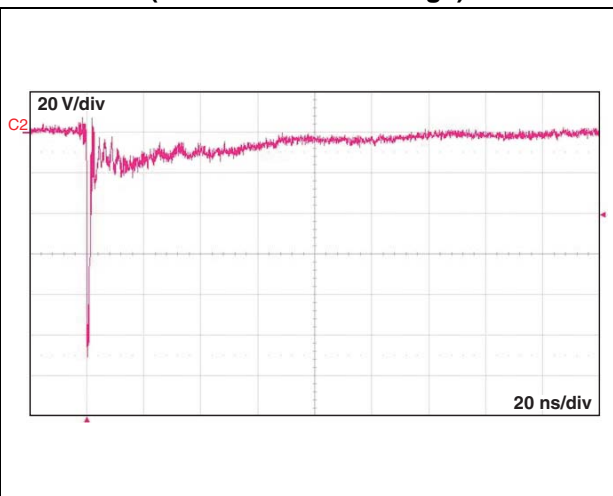
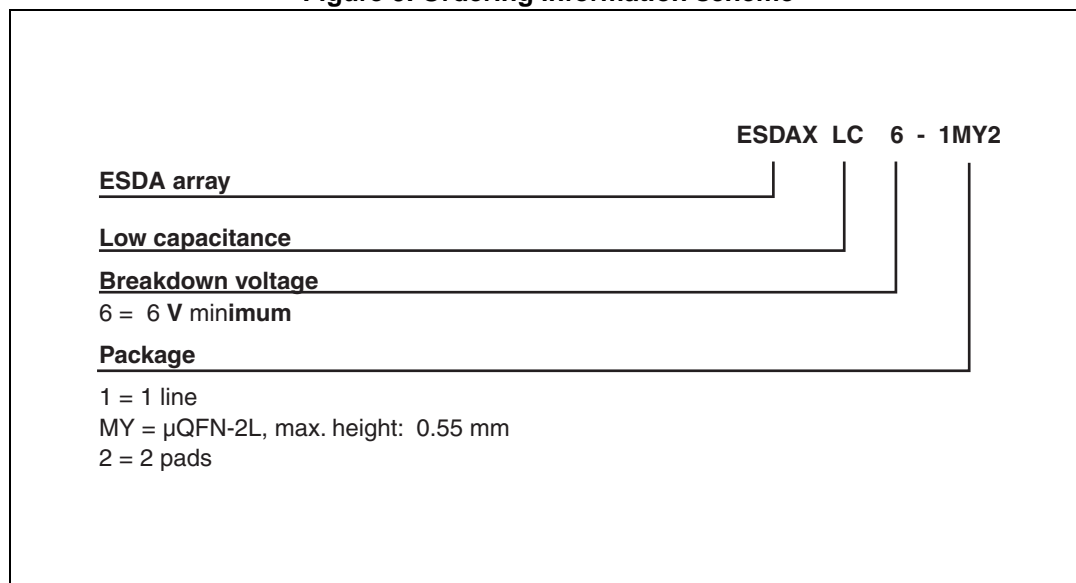


Figure 8. ESD response to IEC 61000-4-2 (-8 kV contact discharge)



2 Ordering information scheme

Figure 9. Ordering information scheme



3 Package information

- Epoxy meets UL 94, V0
- Lead-free package

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK[®] packages, depending on their level of environmental compliance. ECOPACK[®] specifications, grade definitions and product status are available at: www.st.com. ECOPACK[®] is an ST trademark.

Table 3. μ QFN-2L dimensions

Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	0.40	0.47	0.50	0.016	0.019	0.020
A1	0.00		0.05	0.000		0.002
b1	0.45	0.50	0.55	0.018	0.020	0.022
b2	0.45	0.50	0.55	0.018	0.020	0.022
D	0.55	0.60	0.65	0.022	0.024	0.026
E	0.95	1.00	1.05	0.037	0.039	0.041
e	0.60	0.65	0.70	0.024	0.026	0.028
L1	0.20	0.25	0.30	0.008	0.010	0.012
L2	0.20	0.25	0.30	0.008	0.010	0.012

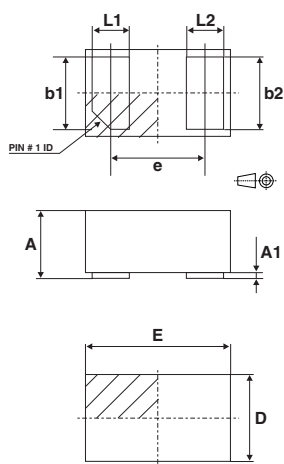
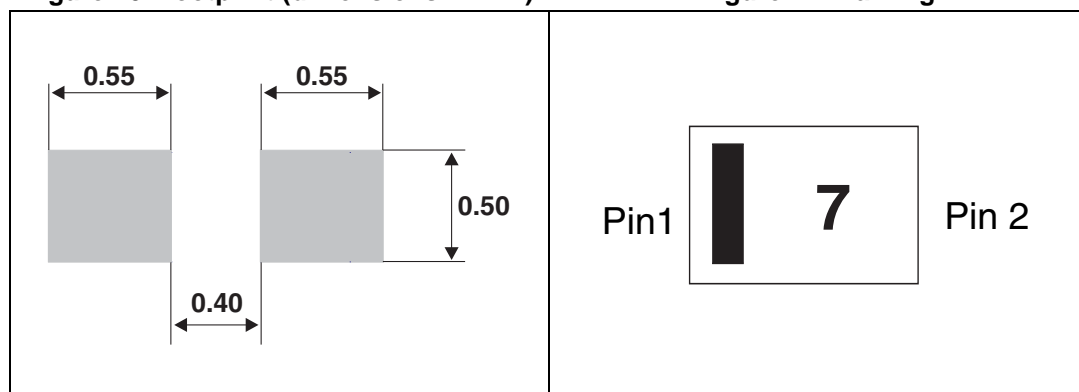


Figure 10. Footprint (dimensions in mm)

Figure 11. Marking

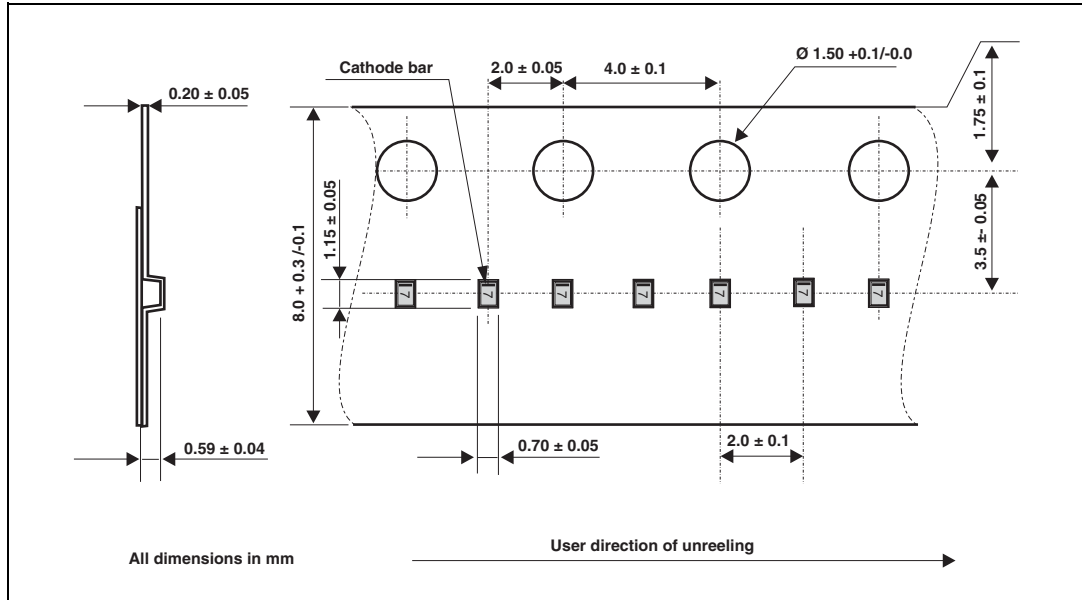


Note: Product marking may be rotated by 90° for assembly plant differentiation. In no case should this product marking be used to orient the component for its placement on a PCB. Only pin 1 mark is to be used for this purpose.

Package information

ESDAXLC6-1MY2

Figure 12. μ QFN-2L tape and reel specification

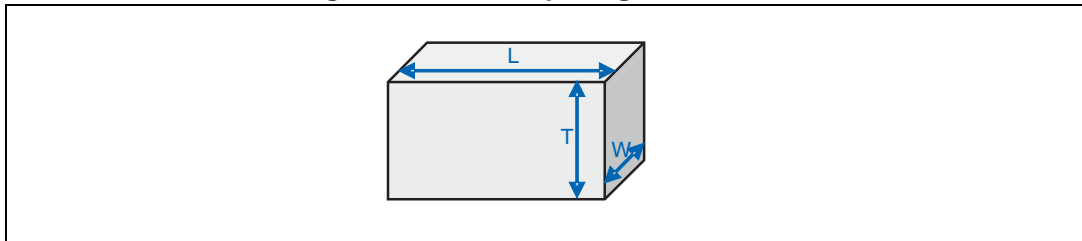


4 Recommendation on PCB assembly

4.1 Stencil opening design

1. General recommendation on stencil opening design
 - a) Stencil opening dimensions: L (Length), W (Width), T (Thickness).

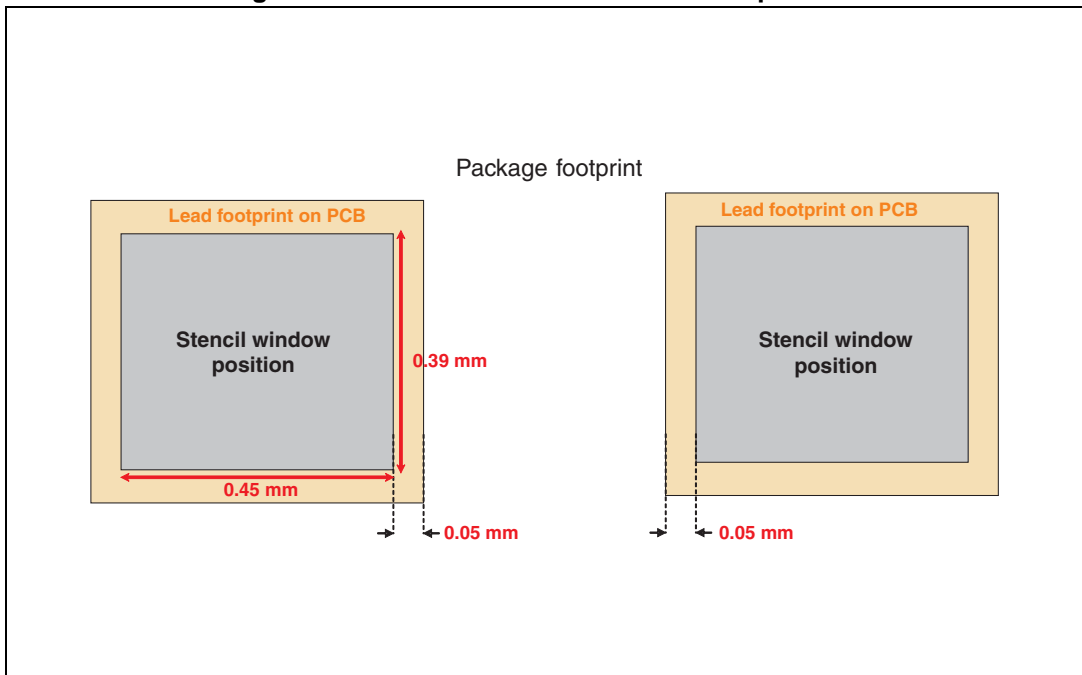
Figure 13. Stencil opening dimensions



- b) General design rule
 - Stencil thickness (T) = 75 ~ 125 μm
 - Aspect Ratio = $\frac{W}{T} \geq 1.5$
 - Aspect Area = $\frac{L \times W}{2T(L + W)} \geq 0.66$

2. Reference design
 - a) Stencil opening thickness: 100 μm
 - b) Stencil opening for central exposed pad: Opening to footprint ratio is 50%.
 - c) Stencil opening for leads: Opening to footprint ratio is 90%.

Figure 14. Recommended stencil window position



4.2 Solder paste

1. Halide-free flux qualification ROL0 according to ANSI/J-STD-004.
2. "No clean" solder paste is recommended.
3. Offers a high tack force to resist component movement during high speed.
4. Solder paste with fine particles: powder particle size is 20-45 μm .

4.3 Placement

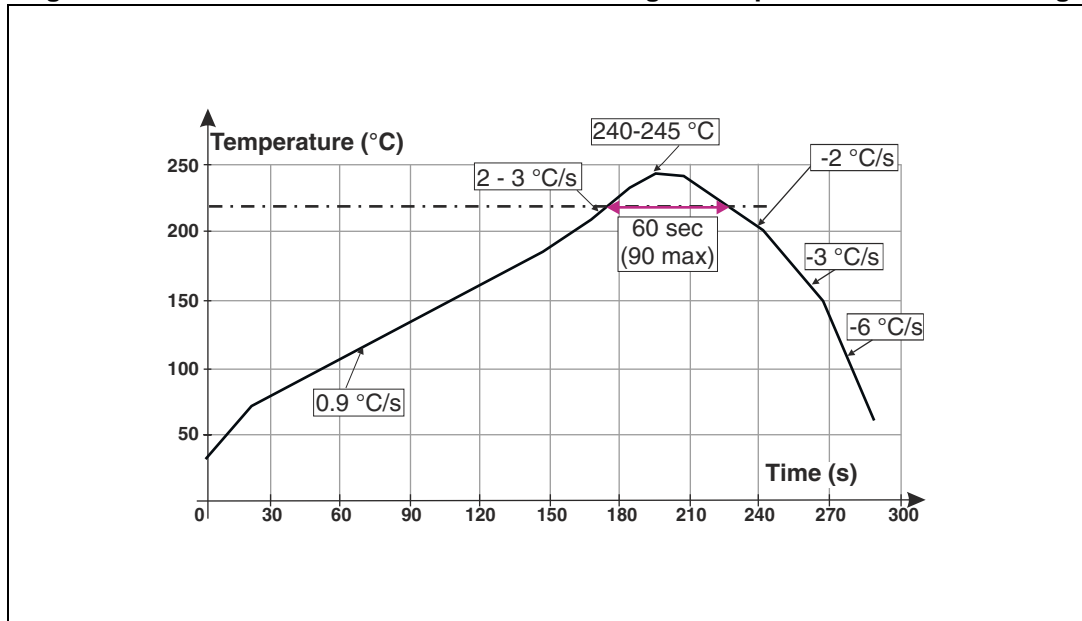
1. Manual positioning is not recommended.
2. It is recommended to use the lead recognition capabilities of the placement system, not the outline centering.
3. Standard tolerance of ± 0.05 mm is recommended.
4. 3.5 N placement force is recommended. Too much placement force can lead to squeezed out solder paste and cause solder joints to short. Too low placement force can lead to insufficient contact between package and solder paste that could cause open solder joints or badly centered packages.
5. To improve the package placement accuracy, a bottom side optical control should be performed with a high resolution tool.
6. For assembly, a perfect supporting of the PCB (all the more on flexible PCB) is recommended during solder paste printing, pick and place and reflow soldering by using optimized tools.

4.4 PCB design preference

1. To control the solder paste amount, the closed via is recommended instead of open vias.
2. The position of tracks and open vias in the solder area should be well balanced. The symmetrical layout is recommended, in case any tilt phenomena caused by asymmetrical solder paste amount due to the solder flow away.

4.5 Reflow profile

Figure 15. ST ECOPACK[®] recommended soldering reflow profile for PCB mounting



Note: Minimize air convection currents in the reflow oven to avoid component movement.
 Maximum soldering profile corresponds to the latest IPC/JEDEC J-STD-020

5 Ordering information

Table 4. Ordering information

Order code	Marking	Package	Weight	Base qty	Delivery mode
ESDAXLC6-1MY2	7	μQFN-2L	0.942 mg	12000	Tape and reel

6 Revision history

Table 5. Document revision history

Date	Revision	Changes
18-Jan-2010	1	Initial release.
23-Sep-2011	2	Updated package name.
31-Mar-2014	3	Updated operating junction temperature range in Table 2 . Updated Figure 3 , Figure 4 , and Figure 6 . Updated graphic and dimension names in Table 3 , Updated Figure 15 .

ESDAXLC6-1MY2

Please Read Carefully:

Information in this document is provided solely in connection with ST products. STMicroelectronics NV and its subsidiaries ("ST") reserve the right to make changes, corrections, modifications or improvements, to this document, and the products and services described herein at any time, without notice.

All ST products are sold pursuant to ST's terms and conditions of sale.

Purchasers are solely responsible for the choice, selection and use of the ST products and services described herein, and ST assumes no liability whatsoever relating to the choice, selection or use of the ST products and services described herein.

No license, express or implied, by estoppel or otherwise, to any intellectual property rights is granted under this document. If any part of this document refers to any third party products or services it shall not be deemed a license grant by ST for the use of such third party products or services, or any intellectual property contained therein or considered as a warranty covering the use in any manner whatsoever of such third party products or services or any intellectual property contained therein.

UNLESS OTHERWISE SET FORTH IN ST'S TERMS AND CONDITIONS OF SALE ST DISCLAIMS ANY EXPRESS OR IMPLIED WARRANTY WITH RESPECT TO THE USE AND/OR SALE OF ST PRODUCTS INCLUDING WITHOUT LIMITATION IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE (AND THEIR EQUIVALENTS UNDER THE LAWS OF ANY JURISDICTION), OR INFRINGEMENT OF ANY PATENT, COPYRIGHT OR OTHER INTELLECTUAL PROPERTY RIGHT.

ST PRODUCTS ARE NOT DESIGNED OR AUTHORIZED FOR USE IN: (A) SAFETY CRITICAL APPLICATIONS SUCH AS LIFE SUPPORTING, ACTIVE IMPLANTED DEVICES OR SYSTEMS WITH PRODUCT FUNCTIONAL SAFETY REQUIREMENTS; (B) AERONAUTIC APPLICATIONS; (C) AUTOMOTIVE APPLICATIONS OR ENVIRONMENTS, AND/OR (D) AEROSPACE APPLICATIONS OR ENVIRONMENTS. WHERE ST PRODUCTS ARE NOT DESIGNED FOR SUCH USE, THE PURCHASER SHALL USE PRODUCTS AT PURCHASER'S SOLE RISK, EVEN IF ST HAS BEEN INFORMED IN WRITING OF SUCH USAGE, UNLESS A PRODUCT IS EXPRESSLY DESIGNATED BY ST AS BEING INTENDED FOR "AUTOMOTIVE, AUTOMOTIVE SAFETY OR MEDICAL" INDUSTRY DOMAINS ACCORDING TO ST PRODUCT DESIGN SPECIFICATIONS. PRODUCTS FORMALLY ESCC, QML OR JAN QUALIFIED ARE DEEMED SUITABLE FOR USE IN AEROSPACE BY THE CORRESPONDING GOVERNMENTAL AGENCY.

Resale of ST products with provisions different from the statements and/or technical features set forth in this document shall immediately void any warranty granted by ST for the ST product or service described herein and shall not create or extend in any manner whatsoever, any liability of ST.

ST and the ST logo are trademarks or registered trademarks of ST in various countries.

Information in this document supersedes and replaces all information previously supplied.

The ST logo is a registered trademark of STMicroelectronics. All other names are the property of their respective owners.

© 2014 STMicroelectronics - All rights reserved

STMicroelectronics group of companies

Australia - Belgium - Brazil - Canada - China - Czech Republic - Finland - France - Germany - Hong Kong - India - Israel - Italy - Japan - Malaysia - Malta - Morocco - Philippines - Singapore - Spain - Sweden - Switzerland - United Kingdom - United States of America

www.st.com